

BGA

LEADED MEDIUM TEMPERATURE
SOLDER PASTE

Sn63/Pb37

MELTING POINT 183°C



SIX CHARACTERISTICS



183°C melting point



Very little tin sticking together



Aluminum box packaging



Tin point is round and full



Premium quality



200 G

Quality Assurance Intimate Service

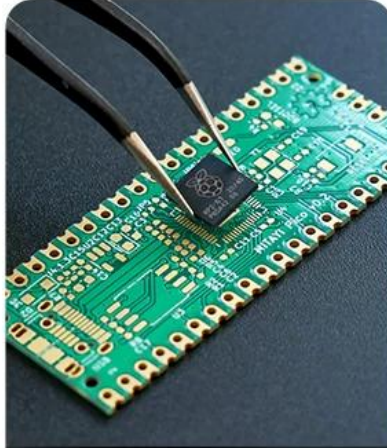
APPLICABLE SCOPE



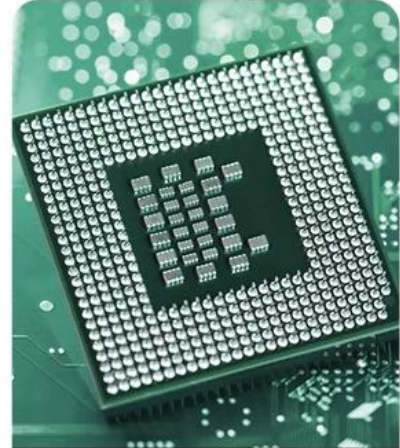
Suitable for SMT patch, BGA soldering, LED



Phone Repair



SMT Patches



BGA planting tin



LED patch



welding work



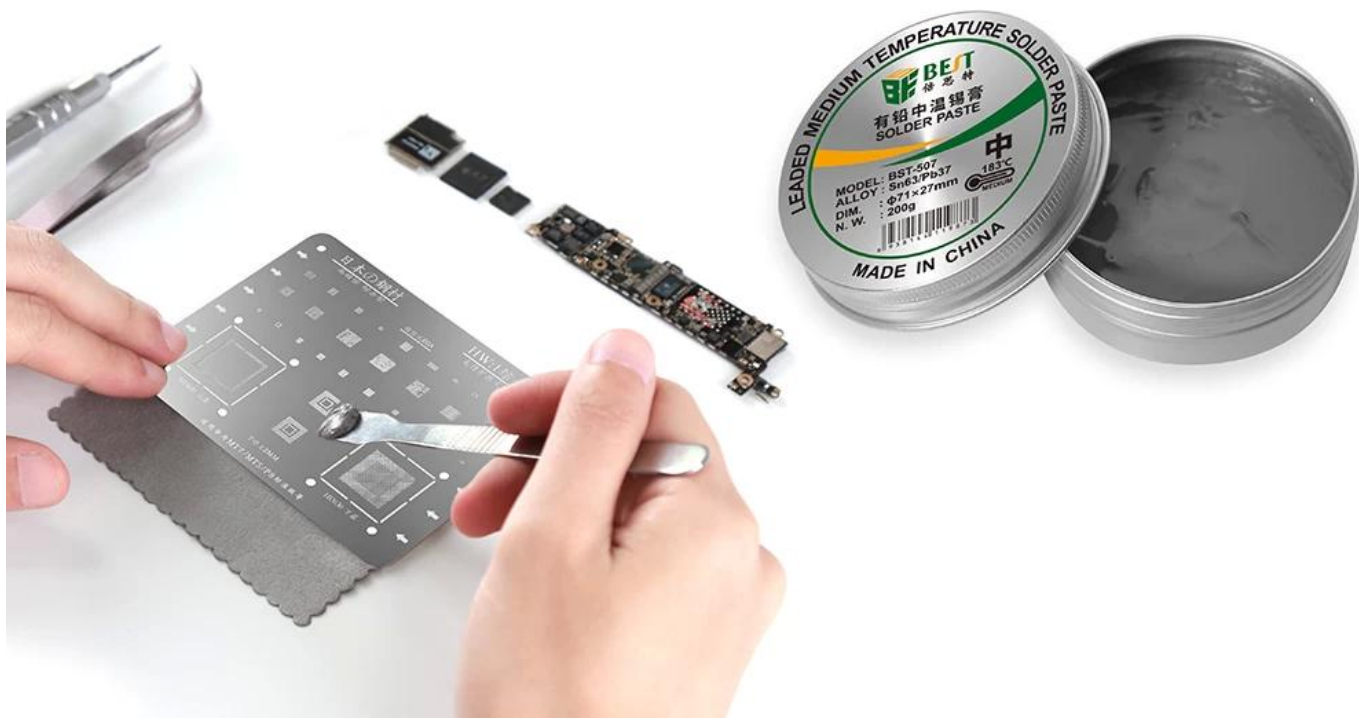
Capacitance resistance

solder paste



MODERATE VISCOSITY

not easy to slump and deviation shift



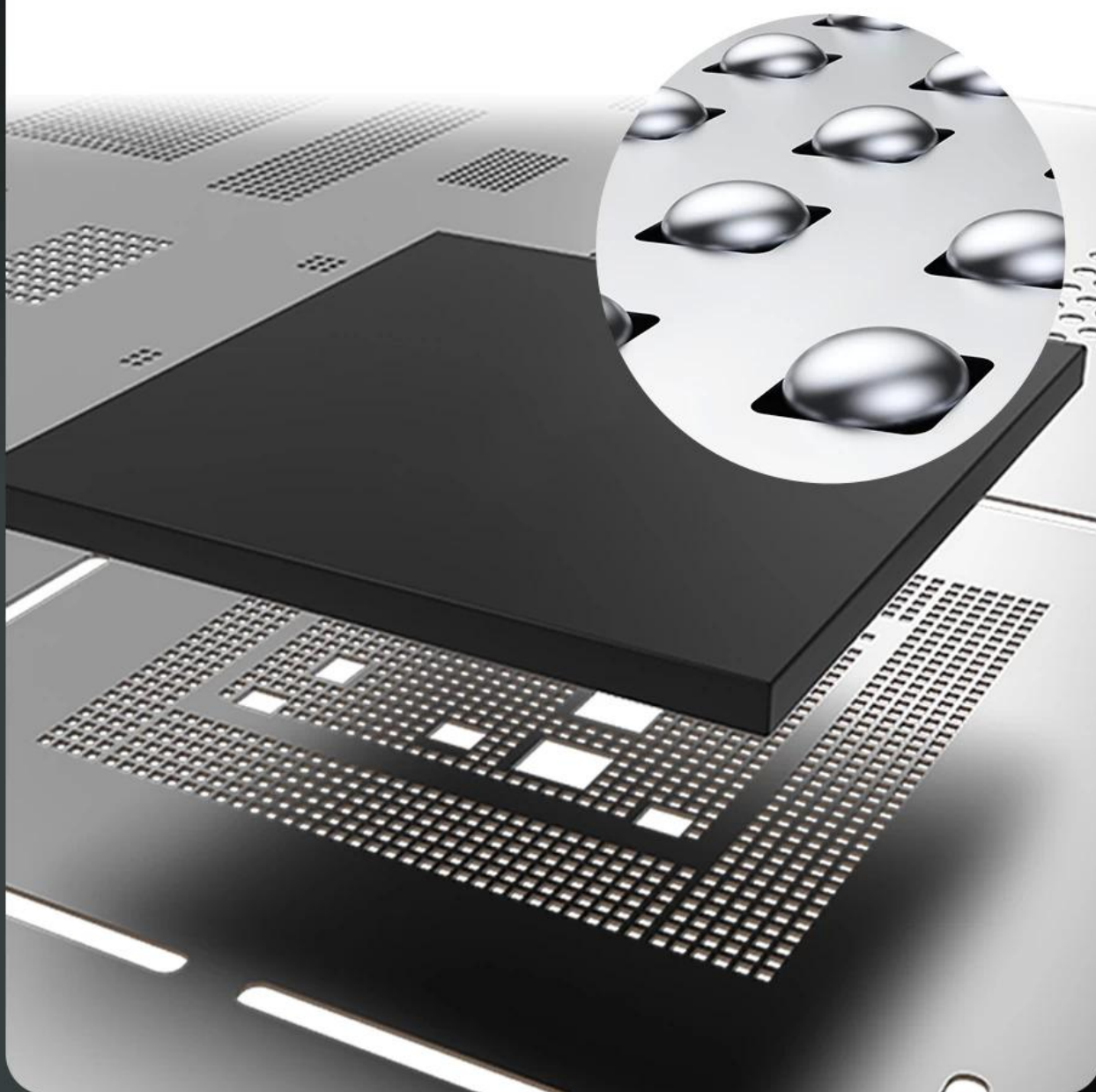


solder paste

TIN POINT BRIGHT AND FULL



High impedance, strong activity, bright and full tin point, easy to solder
No virtual welding or false welding phenomenon



PRODUCT PARAMETERS



Name

Solder paste

Model

BST-507

Material

Sn63/Pb37

N.W.

200g

Package

Aluminum box

Melting point

183°C

Size

70*70*30mm

*The above dimensions are all measured by hand,
if there is any error, it is within 1-3mm.

INSTRUCTIONS FOR USE



1. Usually, the solder paste should be stored in a low temperature environment.
2. Avoid placing the solder paste in the sun.
3. Before opening the package, return the solder paste to room temperature, and be careful not to use a machine for rapid heating.
4. After returning to temperature, it needs to be fully stirred before use.
5. The unused solder paste needs to be stirred again when it is used again. If it is found that the stirring cannot be started, use the special thinner for solder paste and then stir it again. After stirring evenly, it can be used again.
6. The surface of the printed board and the number of solder joints determine the amount of solder paste added to the stencil for the first time. Generally, 200-300g is added for the first time. After printing for a period of time, add a little more appropriately to ensure that the solder paste is printed. When rolling clockwise along the advancing direction of the scraper, the thickness is approximately equal to 1/2 to 3/4 of the height of the metal scraper.

7. The best working conditions of solder paste are: temperature 20~25°C, relative humidity 50~70%, clean, dust-free and anti-static.
8. When mixing new and old solder paste, use 1/4 of the old solder paste and 3/4 of the fresh solder paste to mix together evenly to keep the new and old solder paste in the best state when mixed together.
9. Do not put fresh solder paste and used solder paste into the same bottle. When removing the solder paste from the stencil, replace it with another empty bottle to prevent the fresh solder paste from being contaminated by the old solder paste
10. Precautions, if you accidentally touch your hands and feet, immediately rinse with soap and water, do not rub with your hands, and a small amount of residue can be scrubbed with alcohol.